

ANSYS Semiconductors in 2019 R3

Semiconductors:

The ANSYS semiconductor portfolio of power efficiency, power integrity and reliability solutions achieve ISO 26262 “Tool Confidence Level 1” (TCL1) certification. This certification enables automotive integrated circuit (IC) designers to meet rigorous safety requirements for ADAS and autonomous applications.

Auto chip makers can leverage **ANSYS PowerArtist**, **ANSYS Totem** and **ANSYS RedHawk** family of multi-physics simulations for all ISO 26262 safety-related development projects at any Automotive Safety Integrity Level.

Next-generation system-on-chip (SoC) solutions for automotive, artificial intelligence (AI) and 5G applications are facing shrinking design margins along with increasing cost and time-to-market pressures. ANSYS RedHawk-SC can solve these problems by addressing complex Multiphysics challenges in these designs that use advanced FinFET processes and 3D-IC packaging technologies.

RedHawk-SC in ANSYS 2019 R3 will include major foundry certifications for a comprehensive list of FinFET nodes down to 5nm, significant performance improvement for self-heat and thermal-aware electromigration analysis and orders-of-magnitude reduction in runtime for effective resistance calculation.